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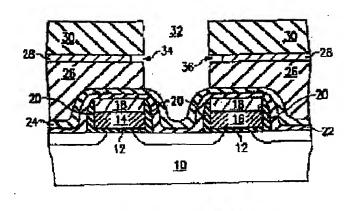
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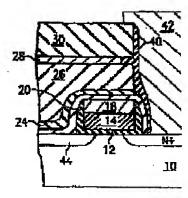
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TITLE

SEMICONDUCTOR DEVICE AND ITS

MANUFACTURE





ABSTRACT :

PROBLEM TO BE SOLVED: To provide a semiconductor device and its manufacturing

method with which the generation of a defective device and the loss of production can be

reduced or removed.

SOLUTION: A contact hole 32 is formed penetrating a conductive layer 28. Then, the conductive layer 28 is undercut (34 and 36). An insulating layer 40 is formed in the contact

hole 32. Then, a contact point 42 is formed in the contact hole 32.

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